



Date Created: 1/23/2004  
Date Issued: 2/25/2004  
PCN # 20040407

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Name: Beh, PaikSwan  
E-Mail: psbeh@epax02.fairchildsemi.com  
Phone: 604-6437211EXT659

PCN Originator

Name: Principi, Fabio E.  
E-mail: Fabio.Principi@notes.fairchildsemi.com  
Phone: 408 822 2565

REL Engineer

Name: Jose, Maggie  
E-mail: Maggie.Jose@notes.fairchildsemi.com  
Phone: 1-408-822-2329

PCN Type: Die Attach Method

Effectivity

Expected 1st Device Shipment Date: 5/17/2004  
Earliest Year/Work Week of Changed Product: 0421  
(Note: Package marking may differ from this format)

Product ID (Description):

This notification pertains to the supervisory products built in a 3ld SOT23 package. Refer to the detailed FSID list at the end of this PCN for the part types affected.

Description of Change:

The current product is built using a non-conductive die attach epoxy ( Ablebond 84-3J ).

The change in process consists in applying a redundant non-conductive layer of epoxy. The new process screen prints a layer of non-conductive epoxy ( Ablebond 8006 ) prior to dispensing the second layer ( Ablebond 84-3J ).

The result is a more robust layer of non-conductive die attach epoxy which has a significantly higher integrity.

Effect of Change:

There is no change in the form, fit or function of the products.  
All the product characteristics are left unchanged with the exception of the improved integrity of the non-conductive die attach epoxy layer.

Qualification:

Qual/REL Plan Numbers

Additional Qualification Data



**RELIABILITY  
QUALIFICATION PLAN**

Q20030084A

*Qualification Device Detail*

<b>Device A:</b>	ILC5061AM23X
<b>Package:</b>	TTB23
<b># Leads:</b>	003

**Process of Record:**

<b>Fabrication Process Flow:</b> 02 - Default Commercial
<b>Fabrication Site/Fabrication Area:</b> RH - RICOH
<b>Assembly Site:</b> UNISEM/ALL MALAYSIA SUBCON'S
<b>Assembly Package:</b> TTB23003 - 003, PLASTIC MOLDED, SOT-23 STD-PRO PKG1, SMD (49)
<b>Assembly Build Diagram:</b>
<b>Comments:</b>

**Subgroup A Precondition Description: - PC1A: MSL(1), PKG(Small), PeakTemp(235c), Cycles(3)**

#	Stress Type	Condition Description	Value	Measurement Units
1	TMCL1	Duration	50	CYCLES
		Low Temperature	-65	C
		High Temperature	150	C
2	VIS	Duration		
		High Temperature	125	C
3	BAKE	Duration	24	HOURS
		High Temperature	125	C
4	MOIS	Duration	168	HOURS
		High Temperature	85	C
		Relative Humidity	85	%RH
5	REFL	Duration		
		High Temperature	235	C
6	FLUX	Duration		
7	RINSE	Duration		
8	DRY	Duration		

**Subgroup B Precondition Description: - PC1A: MSL(1), PKG(Small), PeakTemp(235c), Cycles(3)**

#	Stress Type	Condition Description	Value	Measurement Units
1	TMCL1	Duration	50	CYCLES
		Low Temperature	-65	C

		High Temperature	150	C
2	VIS	Duration		
3	BAKE	Duration	24	HOURS
		High Temperature	125	C
4	MOIS	Duration	168	HOURS
		High Temperature	85	C
		Relative Humidity	85	%RH
5	REFL	Duration		
		High Temperature	235	C
6	FLUX	Duration		
7	RINSE	Duration		
8	DRY	Duration		

**Subgroup C Precondition Description: - PC1A: MSL(1), PKG(Small), PeakTemp(235c), Cycles(3)**

#	Stress Type	Condition Description	Value	Measurement Units
1	TMCL1	Duration	50	CYCLES
		Low Temperature	-65	C
		High Temperature	150	C
2	VIS	Duration		
3	BAKE	Duration	24	HOURS
		High Temperature	125	C
4	MOIS	Duration	168	HOURS
		High Temperature	85	C
		Relative Humidity	85	%RH
5	REFL	Duration		
		High Temperature	235	C
6	FLUX	Duration		
7	RINSE	Duration		
8	DRY	Duration		

**Subgroup Descriptions:**

SUBGROUP	UNIQUE IDENTIFIER DESCRIPTION
A	Qual Lot A
B	Qual Lot B
C	Qual Lot C

**Subgroup POR Detail:**

	A	B	C
Die Revision			
Die Size			
Fab Lot Number			
Fab Location	RH	RH	RH
Assy Lot Number			
Wafer Number			
Assy Location	Y	Y	Y
Subgroup Comments			

## Qualification Stress Test and Sample Size Detail

<b>Device A:</b>	ILC5061AM23X
<b>Package:</b>	TTB23
<b># Leads:</b>	003

### Environmental Stress Detail:

Stress	P/C	Standard	Conditions	Readpoints			Sample		
				TP1	TP2	TP3	A	B	C
ACLV	X		100%RH, 121C	96			77	77	77
HAST1	X		85%RH, 130C, 0V	48	96		77	45	45
HTSL			150C	168	500	1000	77	77	77
TMCL1	X		-65C, 150C	100	500		77	77	77

### WLR/ALR Stress Detail:

Stress	P/C	Standard	Conditions	Readpoints	Sample		
				TP1	A	B	C
DSHR				1	5	5	5

### Affected FSIDs

FM1233ACS3X	FM1233ADS3X	FM1233BDS3X
FM1233BES3X	FM1233BFS3X	FM1233DDS3X
FM1233DES3X	FM1233DFS3X	FM1233ECS3X
FM1233EDS3X	FM6326S3220X	FM6326S3232X
FM6326S3263X	FM6326S3270X	FM6326S3293X
FM6326S3308X	FM6333S3160X	FM6333S3180X
FM6333S3200X	FM6334S3160X	FM6334S3180X
FM6334S3200X	FM803JP3X	FM803JS3X
FM803LP3X	FM803LS3X	FM803MP3X
FM803MS3X	FM803RP3X	FM803RS3X
FM803SP3X	FM803SS3X	FM803TP3X
FM803TS3X	FM809JP3X	FM809JS3X
FM809LP3X	FM809LS3X	FM809MP3X
FM809MS3X	FM809RP3X	FM809RS3X
FM809SP3X	FM809SS3X	FM809TP3X
FM809TS3X	FM810JP3X	FM810JS3X
FM810LP3X	FM810LS3X	FM810MP3X
FM810MS3X	FM810RP3X	FM810RS3X
FM810SP3X	FM810SS3X	FM810TP3X
FM810TS3X	FM811JUX	FM811LUX
FM811MUX	FM811RUX	FM811SUX
FM811TUX	FM812JUX	FM812LUX
FM812MUX	FM812RUX	FM812SUX
FM812TUX	ILC5001AIC27X	ILC5001AIC28X
ILC5001AIC29X	ILC5001AIC327X	ILC5001AIC328X
ILC5001AIC329X	ILC5002AIC331X	ILC5061AC23X
ILC5061AC25X	ILC5061AC26X	ILC5061AC27X
ILC5061AC28X	ILC5061AC29X	ILC5061AIC23X
ILC5061AIC25X	ILC5061AIC26X	ILC5061AIC27X
ILC5061AIC28X	ILC5061AIC29X	ILC5061AIC31X
ILC5061AIC32X	ILC5061AIC34X	ILC5061AIC37X
ILC5061AIC44X	ILC5061AIC46X	ILC5061AIC51X
ILC5061AM23X	ILC5061AM25X	ILC5061AM26X
ILC5061AM27X	ILC5061AM28X	ILC5061AM29X
ILC5061AM31X	ILC5061AM32X	ILC5061AM34X
ILC5061AM37X	ILC5061AM44X	ILC5061AM46X
ILC5061AM51X	ILC5061IC23X	ILC5061IC25X

ILC5061IC26X  
ILC5061IC29X  
ILC5061IC34X  
ILC5061IC46X  
ILC5061M26X  
ILC5061M29X  
ILC5061M34X  
ILC5061M46X  
ILC5062AIC25X  
ILC5062AIC28X  
ILC5062AIC31X  
ILC5062AIC44X  
ILC5062AM24X  
ILC5062AM27X  
ILC5062AM30X  
ILC5062AM34X  
ILC5062AM46X  
ILC5062IC25X  
ILC5062IC28X  
ILC5062IC31X  
ILC5062IC46X  
ILC5062M25X  
ILC5062M28X  
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ILC5062M46X

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ILC5061M31X  
ILC5061M37X  
ILC5062AIC23X  
ILC5062AIC26X  
ILC5062AIC29X  
ILC5062AIC34X  
ILC5062AIC46X  
ILC5062AM25X  
ILC5062AM28X  
ILC5062AM31X  
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ILC5062AIC24X  
ILC5062AIC27X  
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ILC5062AM23X  
ILC5062AM26X  
ILC5062AM29X  
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ILC5062IC24X  
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ILC5062M44X